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**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claim 1 (currently amended): An electronic component comprising:  
a substrate;  
at least one piezoelectric vibrating portion and a connecting portion  
provided on the substrate; and  
a structural piece made of a resin material having a flat plate shape and  
directly covering at least the at least one piezoelectric vibrating portion such that no  
structural elements are disposed between the structural piece and the at least one  
piezoelectric vibrating portion; wherein  
the structural piece has an integrated structure and is provided with a  
concavity including a top portion and side walls covering the at least one piezoelectric  
vibrating portion, the concavity defining a space so as not to disturb at least the  
vibration of the piezoelectric vibrating portion.

Claim 2 (original): An electronic component according to Claim 1, wherein the  
structural piece seals at least the at least one piezoelectric vibrating portion.

Claim 3 (original): An electronic component according to Claim 1, wherein the  
structural piece includes a mounting portion provided on the upper surface thereof, and  
is provided with a connecting wiring for electrically connecting the mounting portion and  
the connecting portion.

Claim 4 (original): An electronic component according to Claim 3, wherein the  
mounting portion does not overlap the connecting portion in a thickness direction of the  
structural piece.

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**Claim 5 (original):** An electronic component according to Claim 1, wherein the concavity is formed by half-processing the structural piece made of a resin material using a laser beam.

**Claim 6 (original):** An electronic component according to Claim 1, wherein the concavity is formed by processing the structural piece made of a resin material by a photolithographic process.

**Claim 7 (original):** An electronic component according to Claim 5, wherein the structural piece is made of a polyimide film or a liquid crystal polymer film.

**Claim 8 (original):** An electronic component according to Claim 6, wherein the structural piece is made from a photosensitive material.

**Claim 9 (original):** An electronic component according to Claim 1, wherein the substrate is made of a material selected from the group consisting of LiTaO<sub>3</sub>, quartz, LiNbO<sub>3</sub> and Li<sub>2</sub>B<sub>4</sub>O<sub>7</sub>.

**Claim 10 (original):** An electronic component according to Claim 1, wherein the at least one piezoelectric vibrating portion includes electrodes made of a material selected from the group consisting of Al, Cu, an Al-Cu alloy and Au.

**Claim 11 (original):** An electronic component according to Claim 1, wherein the structural piece includes at least one through hole.

**Claims 12-17 (canceled).**